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**VRoHS** 

# **Freescale Semiconductor** Advance Information

# **High Speed CAN Interface with Embedded 5.0 V Supply**

The MC33902 is a high speed CAN physical interface. The device includes an internal 5.0 V supply for the CAN bus transceiver, and requires only a connection to a battery line.

The MC33902 provides 4 operation modes, including low power modes with remote and local wake-up.

The device has very low sleep and standby current consumption. **Features**

- High speed CAN interface for baud rates of 40 kb/s to 1.0 Mb/s
- Compatible to ISO11898 standard
- Single supply from battery. No need for a 5.0 V supply for CAN interface
- $\cdot$  I/O compatible from 2.75 V to 5.5 V via a dedicated input terminal (3.3 V or 5.0 V logic compatible)
- Low Power mode with remote CAN wake-up and local wake-up recognition and reporting
- CAN bus failure diagnostics and TXD/RXD pin monitoring, cold start detection, wake-up sources reported through the ERR pin
- Enhanced diagnostics for bus, TXD, RXD and supply pins available through Pseudo SPI via existing terminals EN, STBY and ERR.
- Split terminal for bus recessive level stabilization
- INH output to control external voltage regulator
- Pb-free packaging designated by suffix code EF



 **Figure 1. MC33902 Simplified Application Diagram**

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# **HIGH SPEED CAN PHYSICAL INTERFACE**



**98ASB42565B 14-PIN SOICN**



# **33902**



**INTERNAL BLOCK DIAGRAM**

 **Figure 2. 33902 Simplified Internal Block Diagram**

# **PIN CONNECTIONS**





# **Table 1. 33902 Pin Definitions**



ELECTRICAL CHARACTERISTICS *MAXIMUM RATINGS*

# **ELECTRICAL CHARACTERISTICS**

# *MAXIMUM RATINGS*

# **Table 2. Maximum Ratings**

All voltages are with respect to ground, unless otherwise noted. Exceeding these ratings may cause a malfunction or permanent damage to the device.



# *STATIC ELECTRICAL CHARACTERISTICS*

# **Table 3. Static Electrical Characteristics**

Characteristics noted under conditions 5.5 V ≤ V<sub>SUP</sub> ≤ 27 V, -40°C ≤ T<sub>A</sub> ≤ 125°C, GND = 0 V, unless otherwise noted. Typical values noted reflect the approximate parameter means at T<sub>A</sub> = 25°C under nominal conditions, unless otherwise noted.



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- - 0.0 -

5.0 70

 $-12$  V <  $V_{\text{SPLIT}}$  <  $+12$  V -22 V <  $V_{\text{SPLIT}}$  < +35 V

# *DYNAMIC ELECTRICAL CHARACTERISTICS*

### **Table 4. Dynamic Electrical Characteristics**

Characteristics noted under conditions 5.5 V ≤ V<sub>SUP</sub> ≤ 27 V, -40°C ≤ T<sub>A</sub> ≤ 125°C, GND = 0 V, unless otherwise noted. Typical values noted reflect the approximate parameter means at T<sub>A</sub> = 25°C under nominal conditions, unless otherwise noted.



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# *TIMING DIAGRAMS*



<span id="page-8-0"></span>EN and ERR state changed at STBY rising edge

# **Figure 4. P\_SPI Timing**



 **Figure 5. Propagation Loop Delay TXD to RXD**







 **Figure 7. Test Circuit for Timing Characteristics**

# **FUNCTIONAL DESCRIPTION**

# *FUNCTIONAL PIN DESCRIPTION*

# **TRANSMIT DATA (TXD)**

This input is the CAN transmit data pin. It is the interface from the MCU to the output on the CAN bus. If TxD is low (dominant), then the signal on the CAN bus will be dominant (CANH is  $~5.0$  V and CANL is  $~0$  V). If TxD is high (recessive), then the signal on the CAN bus will be recessive (CANH and CANL will be ~2.5 V). The TxD thresholds are 3.3 V and 5.0 V compatible (depending on VIO voltage) to accommodate the implementation of various MCUs. There are three slew rates available, which are selected via the Pseudo SPI.

# **GROUND (GND)**

Ground termination pin.

# **VOLTAGE DIGITAL DRAIN (VDD)**

This is the dedicated embedded supply voltage for the CAN interface. A capacitor must be connected to this pin. CAN interface current is sourced from this pin if device is in transmit and receive mode. In low power modes, current for the CAN interface is sourced directly from the VSUP pin.

# **RECEIVE DATA (RXD)**

This output pin is the CAN receive data. It is the interface to the MCU, which reports the state of the CAN bus. If the CAN bus is recessive (CANH and CANL ~2.5 V), then the signal on RxD will be high (recessive). If the CAN bus is dominant (CANH is  $~5.0$  V and CANL is  $~0$  V), then the signal on RxD will be low (dominant). This pin is also an active-low wake-up flag in low power, which reports a wakeup event to the MCU. RxD thresholds are 3.3 V and 5.0 V compatible (depending on the VIO voltage) to accommodate the implementation of various MCUs.

# **VOLTAGE SUPPLY FOR I/O (VIO)**

This is the dedicated input supply pin to determine voltage thresholds for the digital input/output pins. The VIO thresholds range from 2.75 V to 5.5 V to accommodate the implementation of 3.3 V or 5.0 V MCUs.

# **ENABLE (EN)**

This is the enable input pin for device static mode control. This pin is connected to the MCU to place transceiver in the desired mode. Functional voltage thresholds are determined by VIO voltage to accommodate the implementation of 3.3 V or 5.0 V MCUs. MOSI (Master Out, Slave In) during Pseudo SPI communication.

# **INHIBIT (INH)**

The inhibit output pin controls an external power supply regulator. When the INH output is low, the external regulator is expected to shut down, which would then turn off the MCU and any other device that is powered up by the external regulator. This should considerably decrease the module's current consumption.

# **ACTIVE LOW ERROR (ERR)**

The dedicated active low flag reporting pin reports any static errors, flags and wake-ups to the MCU depending on devices operating state. MISO (Master In, Slave Out) during Pseudo SPI communication.

# **WAKE (WAKE)**

The Wake input pin is used to wake-up the device from sleep mode after a Battery to Gnd, or Gnd to Battery transition. This pin is usually connected to an external switch in the application module, and SHOULD NOT be left open. If Wake pin functionality is not being used, it should be connected to GND to avoid false wake-ups. This pin exhibits a high-impedance for low input current when implemented below 18 V. If voltage exceeds 18V at the pin, a series resistor should be used to limit the amount of current that the device will start sinking.

# **VOLTAGE SUPPLY (VSUP)**

This is the power supply input pin. The DC operating voltage for the device is 5.5 V to 27 V. A reverse battery protection diode should be implemented. This pin is able to sustain automotive transient conditions, such as 40 V load dumps and 27 V jump start conditions. The device's quiescent sleep current is typically around 10 µA.

# **SPLIT (SPLIT)**

This is the output pin for middle point connection of CANH and CANL when implementing split termination. Pin voltage is typically around half of VDD (2.5 V) with or without loads. This pin must be left open if split CAN termination is not implemented.

# **CAN HIGH (CANH)**

This is the CAN High input/output pin. CANH circuitry is design to work as a high side switch connected to VDD. In the recessive state, this switch is turned off and CANH is then biased to SPLIT voltage or GND, depending on device's operating state. In the dominant state, the switch is turned on and CANH is biased to VDD voltage. The CANH pin is protected and diagnostics reporting is available against short to Battery, Gnd, and 5.0 V (VDD).

# **CAN LOW (CANL)**

This is the CAN Low input/output pin. CANL circuitry is design to work as a low side switch connected to GND. In the recessive state, this switch is turned off and CANL is then biased to SPLIT voltage or Gnd, depending on device's operating state. In the dominant state, the switch is turned on and CANL is biased to GND voltage. The CANL pin is protected and diagnostics reporting is available against short to Battery, Gnd, and 5.0 V (VDD).

# **STANDBY (STBY)**

This is the standby input pin for device static mode control. This pin is connected to the MCU to place transceiver in the desired mode. Functional voltage thresholds are determined by VIO voltage to accommodate the implementation of 3.3 V or 5.0 V MCUs. CLK (Clock) during Pseudo SPI communication.

# **FUNCTIONAL DEVICE OPERATION**

# *OPERATIONAL MODES*



#### <span id="page-12-5"></span>Notes

- 1. Coming from Standby mode
- <span id="page-12-0"></span>2. If  $V_{1/2}$  is still switched on
- <span id="page-12-4"></span>3. Coming from Normal mode
- <span id="page-12-2"></span>4. If batfail flag and wake-up flag are cleared. An attempt to enter Sleep mode without batfail and wake-up flag cleared has no effect
- <span id="page-12-3"></span>5. Limited current capability, to maintain the capacitor at  $V_{DD}$  charged.
- <span id="page-12-1"></span>6. A high level on INH will report a wake-up in Sleep mode
- <span id="page-12-6"></span>7. After 4 TXD pulses rising edge

#### **Figure 8. State Diagram**

#### FUNCTIONAL DEVICE OPERATION *OPERATIONAL MODES*

#### <span id="page-13-3"></span>**Table 5. Functional Table**



<span id="page-13-0"></span>Notes

8. With limited current capability, in order to maintain the capacitor at  $V_{DD}$  pin charged

<span id="page-13-1"></span>9. Provided if  $V_{10}$  > 2.5 V.

<span id="page-13-2"></span>10. Before 4th TX pulse rising edge



 $V_{DD}$  low illustration,  $V_{SUP} > V_{SUP}$  low ( $V_{SUP} > 5.8$  V)

 $\rm V_{DD}$  low illustratio<u>n, cr</u>anking pulse  $\rm V_{SUP}$  < V $_{SUP}$  low (V $_{SUP}$  < 5.8 V) and CRANK bit low in P\_SPI register.

1) See figure on ERR reporting

2) V<sub>DD</sub> is re enabled when V<sub>SUP</sub> recovers (V<sub>SUP</sub> low flag goes from H to L) or by a mode change via EN and STBY input.<br>3) Capacitor charged maintained by internal device current source

# **Figure 9. V<sub>DD</sub> Low Illustration**

# **DEVICE STATE DESCRIPTION**

#### **STANDBY MODE**

Standby mode is a reduced current consumption mode. CANH and CANL lines are terminated to GND, the SPLIT pin is high-impedance. In order to monitor bus activities, the CAN wake-up receiver is ON, INH output remains ON. The voltage on VIO should be maintained.

The VDD regulator is ON with limited current capability, in order to maintain the capacitor at VDD charged and allow a fast transition to Normal mode and fast CAN communication.

Wake-up events occurring on the CAN bus or on the WAKE pin are reported by a low level of the ERR and RXD pins. The Standby mode is also the first mode entered after a device power up. In this case, the VDD regulator is activated to charge the  $V_{DD}$  capacitor, and then the regulator enters the reduced current capability mode, in order to optimize and reduce system current consumption. Depending upon the  $V_{DD}$  capacitor 's Equivalent Series Resistance (ESR), a voltage drop can be observed. See [Figure 10.](#page-14-0)



**Figure 10. V<sub>DD</sub> Regulator Start-up** 

#### <span id="page-14-0"></span>**NORMAL MODE**

In Normal mode, both the CAN driver and receiver are ON. In this mode, the CAN bus is controlled by the TXD pin level, and the CAN bus state is reported on the RXD pin.

The VDD regulator is ON. It supplies the CAN driver and receiver.The SPLIT pin is active and a 2.5 V biasing is provided on the SPLIT output pin.

In Normal mode, the  $\overline{\text{ERR}}$  pin reports the wake-up source and the bus failure, after 4 TXD pulses. Normal mode is entered by setting the EN and STBY pins high. Entering Normal mode will clear the BATFAIL flag.

#### **LISTEN ONLY MODE**

This mode is used to disable the CAN driver, but leave the CAN receiver active. In this mode, the device is only able to report the CAN state on the RXD pin. The TXD pin has no effect on CAN bus lines. This mode is entered by setting the EN and STBY pins to [0, 1].

In this mode, coming from Normal mode, the ERR pin reports local failures occurring on the TXD and RXD pins, and V<sub>DD</sub> low. When this mode is entered from the Standby mode, the ERR pin reports the BATFAIL flag.

The VDD regulator is ON. The SPLIT pin is active and a 2.5 V biasing is provided on the SPLIT output pin.

#### **GO TO SLEEP MODE**

Go to sleep is an intermediate mode to ultimately set the device in Sleep mode. The go to sleep is entered by setting the EN and STBY pins to [1, 0]. If the EN and STBY pins are maintained to [1,0] for a time longer than  $t_H$ , the Sleep mode is automatically entered. In go to Sleep mode, the VDD regulator remains in its previous state and the SPLIT pin is deactivated. INH is active.

#### **SLEEP MODE**

The Sleep mode is a low power mode. It is entered from the Go To Sleep mode by setting the EN and STBY pins to [1 0], and automatically from Go To Sleep mode after  $t_H$ . In Sleep mode, the VDD regulator is turned off and the SPLIT pin is deactivated, INH is high-impedance.

In Sleep mode and Go To Sleep mode, the device is able to wake-up on CAN bus activity or transitions on the WAKE pin. A wake-up from Sleep mode will set the device in Standby mode. Sleep mode is also automatically reached if the voltage at VIO is below the VIO<sub>TH</sub> for more time than TVIO-SLP.

# **DEVICE MAIN FLAGS DESCRIPTION:**

This section describes the flags available when the device is controlled via the EN and STBY pins in a static manner (no P SPI control). Additional information and control are possible using the Pseudo SPI (refer to [Extended device](#page-20-0)  [operation\)](#page-20-0).

#### **BATFAIL**

This flag is set to signal that the voltage on the VSUP pin has dropped below VBF $_{THS}$ , particularly after the device was disconnected from the battery. In Listen Only mode, the BATFAIL flag will be available on the ERR pin, coming from standby, Go To Sleep and Sleep modes. When  $V_{\text{SUP}}$  is below VBF threshold, all internal flags and registers are reset to their initial condition.

#### **CAN Bus Wake-up (WU)**

From Standby or Sleep mode, this flag is set if a correct pattern has been received on the CAN bus. This wake-up is reported on ERR and RXD pins by a low level in Standby mode, as well as in Sleep mode if VIO is present.

The flag is cleared by leaving the Normal mode or by a P SPI reading.

#### **WAKE Pin - Local Wake-up (WU)**

From the Standby, Go To Sleep or Sleep mode, this flag is set if a transition on the WAKE pin is detected. This wake-up is reported on the ERR pin by a low level in Standby mode, as well as in Sleep mode if VIO is present.

The wake-up flag is cleared by leaving the Normal mode or by P\_SPI reading.

#### **Wake-up Source**

Wake-up source is reported on the ERR pin by entering Normal mode, before 4 TX pulses. The ERR pin is low to indicate a local wake-up, and high to indicate CAN wake-up.

#### **Local Failure**

This flag is a logic  $\kappa$ OR» of the following failures: TXD dominant clamping, RXD recessive clamping, TXD-to-RXD short-circuit and VDD low condition. This flag is reported in Listen Only on the ERR pin coming from Normal mode.

Using the P\_SPI, it is possible to get detailed failure information.

#### **BUS Failure**

The BUS failure flag is set if the CAN transceiver detects a bus line short-circuit condition to VSUP, VDD, or GND, during five consecutive dominant-recessive cycles on the TXD pin. In addition, this flag reports a bus dominant clamping condition. In Normal mode, the bus failure flag is available on the ERR pin.

Using the P\_SPI, it is possible to get detailed failure information.

#### **VDD low**

 $V_{DD}$  low flag is set in Normal and Listen Only mode when  $V_{DD}$  is below the  $V_{DD}$  low threshold. After a time longer than  $t<sub>VDD-CANOFF</sub>$ , the CAN is disabled and after a time longer than  $t_{\text{VDDOFF}}$ , the  $V_{\text{DD}}$  regulator is disabled to avoid a battery discharge.

If the CRANK bit is set high, the  $V_{DD}$  regulator and CAN will not be disabled if  $V_{\text{SUP}}$  is below  $V_{\text{SUV}}$ . When  $V_{\text{SUP}}$  is above  $V_{SUV}$ , the CRANK bit has no effect.

 $V_{DD}$  low flag is reported in Normal and Listen Only mode, so the user can differentiate between local and bus failures by changing modes and observing ERR staying low.

In case of a double failure (local and bus failure) at the same time, the results will be the same: ERR low in Normal and in Listen Only mode. However, this is unlikely to occur.

This flag is cleared when entering low power, or when  $V_{DD}$ is above  $V_{DD}$  low threshold, plus the P\_SPI reading.

The  $V_{DD}$  regulator is re enabled as soon as  $V_{SUP}$  rises above  $V_{\text{SUP}}$  low, or by a mode change (refer to the crank pulse illustration).

The CAN is re-enabled as soon as  $V_{DD}$  is above  $V_{DD}$  low threshold. (refer to crank pulse illustration).

# **ERR Pin**

The ERR pin reports various information depending upon the device state, the device state transition, and event on the TXD pin.

[Table 6](#page-15-0) shows the diagnostic flag availability when the device is controlled in a static manner.



#### <span id="page-15-0"></span>**Table 6. "Static" Diagnostic Flags**

**WAKE-UP EVENT** CAN Wake-up or Local Wake-up =>  $\overline{\text{ERR}}$  low **LOCAL FAILURE** VDD low, TXD-PD, RXD-PR, TXD short to RXD => ERR low **BATFAIL BUS FAILURE,**  $\frac{4 \text{ dominant}}{4 \text{ volume}} \qquad \frac{1}{2} \qquad \text{VD}$  VDDlow, Bus dom, **WAKE-UP SOURCE** Local Wake-up => ERR low; CAN Wake-up => ERR high **GO TO SLEEP STANDBY SLEEP** CANH or CANL short to GND<br>5.0 V or V<sub>BAT</sub> => ERR low **LISTEN ONLY NORMAL**  $STBY = 0$  $EN = X$  $STBY = 1$  $EN = 0$  $STBY = 1$  $EN = 1$  $STBY = 0$  $EN = X$  $STBY = 0$  $EN = X$  $STBY = 0$  $EN = X$ pulses at TXD  $STRY = 1$  $EN = 0$  $STBY = 1$  $EN = 1$  $STBY = 1$  $EN = 1$  $STRY = 1$  $EN = 0$ *DEVICE MODE ERR MEANING*  $STBY = 1$  $EN = 1$  $STBY = 1$  $EN = 0$  $STRY = 0$  $EN = X$ V<sub>SUP</sub> Low =>ERR high

[Figure 11](#page-16-0) shows the meaning of the ERR pin versus the device state, the state transition and the events on TXD.

#### **Figure 11. ERR versus device state**

# <span id="page-16-0"></span>**CAN INTERFACE DESCRIPTION:**

#### **CAN Interface Supply**

The supply voltage for the CAN driver is the VDD pin. The CAN interface also has a supply path from the battery line, through the VSUP pin. This path is used in CAN Sleep mode to allow wake-up detection.

During CAN communication (transmission and reception), the CAN interface current is sourced from the VDD pin. During CAN low power mode, the current is sourced from the VSUP pin.

#### **CAN Driver Operation in Normal Mode**

The CAN driver will be enabled as soon as the device is in Normal mode and the TXD pin is recessive.

When the CAN interface is in Normal mode, the driver has two states: recessive or dominant. The driver state is controlled by the TXD pin. The bus state is reported through the RXD pin.

When TXD is high, the driver is set in the recessive state, and CANH and CANL lines are biased to the voltage set at VDD divided by 2, approx. 2.5 V.

When TXD is low, the bus is set into the dominant state, and the CANL and CANH drivers are active. CANL is pulled low and CANH is pulled high.

The RXD pin reports the bus state: CANH minus the CANL voltage is compared versus an internal threshold (a few hundred mV).

If "CANH minus CANL" is below the threshold, the bus is recessive and RXD is set high.

If "CANH minus CANL" is above the threshold, the bus is dominant and RXD is set low.

The SPLIT pin is active and provide a 2.5 V biasing to the SPLIT output.

#### **Normal Mode and Slew Rate Selection**

The CAN signal slew rate selection is done via the P\_SPI. By default, and if no P\_SPI is used, the device is in the fastest slew rate. Three slew rates are available. The slew rate controls the recessive to dominant and dominant to recessive transitions, which are also dependent on CANH and CANL capacitance. This also affects the delay time from the TXD pin to the bus, and from the bus to RXD. The loop time is thus affected by the slew rate selection.

#### **Minimum Baud rate**

The minimum baud rate is determined by the shortest TXD permanent dominant timing detection. The maximum number of consecutive dominant bits in a frame is 12 (6 bits of active error flag and its echo error flag).

The shortest TXD dominant detection time of 300 µs leads to a single bit time of: 300  $\mu$ s / 12 = 25  $\mu$ s.

So the minimum Baud rate is  $1/25$   $\mu$ s = 40 kBaud.



#### **Termination**

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The device supports the two main types of bus terminations:

- Differential termination resistors between CANH and CANL lines
- Split termination concept, with the mid point of the differential termination connected to GND through a capacitor, and to the SPLIT pin
- Refer to Typical Application and Bus Termination Options [and WAKE Pin Configuration on page 27](#page-26-0)

#### **Low Power Mode**

In low power mode, the CAN is internally supplied from the VSUP pin.

In low power mode, the CANH and CANL drivers are disabled, and the receiver is also disabled. CANH and CANL have a typical 40 k $\Omega$  impedance to GND. The wake-up receiver can be activated if wake-up is enabled by the P\_SPI command. The SPLIT pin is high-impedance.

When the device is set back into Normal mode, CANH and CANL are set back into the recessive level. This is illustrated in the following diagram.





#### **Wake-up**

<span id="page-17-0"></span>.

When the CAN interface is in Sleep mode with wake-up enabled, the CAN bus traffic is detected. The CAN bus wakeup signal is a pattern wake-up. CAN wake-up cannot be disabled.

#### **CAN Wake-up Report**

The CAN wake reports depend upon the low power mode selected, Sleep or Standby. In Sleep mode, the INH pin is activated. In Standby mode, the VIO voltage is present and the wake-up is reported by the ERR and RXD pin low level. Ref to [Table 5](#page-13-3).

#### **Pattern Wake-up**

In order to wake-up the CAN interface, the wake-up receiver must receive a series of 3 consecutive valid dominant pulses. This is the default setting in which the CAN WU-pattern bit is set low. CAN WU-pattern bit can be set high by P\_SPI, and the wake up will occur after a single pulse duration of a minimum of 4.0 µs.

A valid dominant pulse should be longer than  $t_{PWIDTH}$ . The 3 pulses should occur in a time frame of 120 µs to be considered valid. When 3 pulses pass these criteria the wake signal is detected. This is illustrated in **Figure 13**.





# **CAN BUS DIAGNOSTIC**

The aim is to implement a diagnostic of bus short-circuit to GND, VBAT, and the internal application circuit board 5.0 V. Several comparators are implemented on the CANH and

CANL lines. These comparators monitor the bus level in the recessive and dominant states. The information is then managed by the logic circuitry to properly determine the failure and report it.



#### **Figure 14. CAN Bus Simplified Structure Truth Table for Failure Detection**

[Table 7](#page-18-0) indicates the state of the comparators in case of a bus failure, and depending upon the driver state.

#### Failure description **Driver recessive state Driver dominant state Lg (threshold 1.75 V) Hg (threshold 1.75 V) Lg (threshold 1.75 V) Hg (threshold 1.75 V)** No failure 1 1 0 1 CANL to GND 0 0 0 1 CANH to GND 0 0 0 0 **Lb (threshold VSUP-2.0 V) Hb (threshold VSUP-2.0 V) Lb (threshold VSUP-2.0 V) Hb (threshold VSUP-2.0 V)** No failure 0 0 0 0 CANL to VBAT 1 1 1 1 CANH to VBAT 1 1 0 1  $\overline{L5}$  (threshold V<sub>DD</sub><sup>-0.43</sup> V) **H5** (threshold V<sub>DD</sub><sup>-0.43</sup> V) **L5** (threshold V<sub>DD</sub><sup>-0.43</sup> V) **H5** (threshold V<sub>DD</sub><sup>-0.43</sup> V) No failure 0 0 0 0 CANL to 5.0 V | 1 | 1 | 1 | 1 | 1 | 1 | 1 CANH to 5.0 V 1 1 0 1

#### <span id="page-18-0"></span>**Table 7. Failure Detection Truth Table**

#### **Detection Principle**

In the recessive state, if one of the two bus lines are shorted to GND, VDD, or VBAT, the voltage at the other line follows the shorted line, due to the bus termination resistance. For example: if CANL is shorted to GND, the CANL voltage is zero, the CANH voltage measured by the Hg comparator is also close to zero.

In the recessive state, the failure detection to GND or VBAT is possible. However, it is not possible with the above implementation to distinguish which of the CANL or CANH lines are shorted to GND or VBAT. A complete diagnostic is possible once the driver is turned on, and in the dominant state.

#### **Number of Samples for Proper Failure Detection**

The failure detector requires at least one cycle of the recessive and dominant states to properly recognize the bus failure. The error will be fully detected after 5 cycles of the recessive-dominant states. As long as the failure detection

circuitry has not detected the same error for 5 recessivedominant cycles, the error is not reported.

#### **Bus clamping detection**

If the bus is detected to be in dominant for a time longer than ( $t_{\text{DOM}}$ ), the bus failure flag is set and the  $\overline{\text{ERR}}$  is set low in Normal mode.

Such conditions could occur if the CANH line is shorted to a high voltage. In this case, current will flow from the high voltage short-circuit through the bus termination resistors (60  $\Omega$ ) and then in the Split terminal (if used), and through the device CANH and CANL input resistors, which are terminated to an internal 2.5 V biasing or to GND (Sleep mode).

Depending upon the high voltage short-circuit, the number of nodes, usage of split terminal,  $R_{IN}$  actual resistor, and node state (sleep or active), the voltage developed across the bus termination can be sufficient to create a positive dominant voltage between CANH and CANL. The RXD pin will be low. This would prevent the start of any CAN

communication, and thus a proper failure identification (requires 5 pulses on TXD). The bus dominant clamp circuit will help to determine such failure situation.

#### **RX Permanent Recessive Failure**

The aim of this detection is to diagnose an external hardware failure at the RX output pin and ensure that a

permanent failure at RX does not disturb the network communication. If RX is shorted to a logic high signal, the CAN protocol module within the MCU will not recognize any incoming message. In addition it will not be able to easily distinguish the bus idle state and can start communication at any time. In order to prevent this, an RX failure detection is necessary.



The RX flag is not the RXPR bit in the LPC register, and neither is the CANF in the INTR register.

Figure 15. RX Path Simplified Schematic, Rx Short to V<sub>DD</sub> Detection

#### **Implementation for Detection**

The proposed implementation is to sense the RXD output voltage at each low to high transition of the differential receiver. Excluding the internal propagation delay, the RXD output should be low when the differential receiver is low. In case of an external short to VDD at the RXD output, RXD will be tied to a high level and can be detected at the next low to high transition of the differential receiver.

As soon as the RXD permanent recessive is detected, the RXD driver is deactivated.

Once the error is detected, the flag is latched and the driver is disabled. The error is reported at ERR pin and via P\_SPI.

#### **Recovery Condition**

The internal recovery is done by sampling a correct low level at the Bus as shown in **Figure 16**.



<span id="page-19-0"></span>Figure 16. RX Path Simplified Schematic, Rx Short to V<sub>DD</sub> Detection

#### **Important Information for Bus Driver Reactivation RXD**

The driver stays disabled until the failure is cleared (RX is no longer permanent recessive). One transition on the CAN bus (internal differential receiver transition), and the bus driver is activated by entering into Normal mode.

### **TXD PERMANENT DOMINANT**

#### **Principle**

If the TXD is set to a permanent low level, the CAN bus is set into dominant level, and no communication is possible. The 33902 has a TXD permanent time out detector. After the timeout, the bus driver is disabled and the bus is released into a recessive state. The TXD permanent flag is set.

#### **Recovery**

The TXD permanent dominant is used and activated in case of a TXD short to RXD. The recovery condition for a TXD permanent dominant (recovery means the re-activation of the CAN drivers) is done by entering into a Normal mode controlled by the MCU, or when TXD is recessive, while RXD changes from recessive to dominant.

# **TXD TO RXD SHORT CIRCUIT:**

#### **Principle**

If TXD is shorted to RXD during incoming dominant information, RXD is set low. Consequently, the TXD pin is low and drives CANH and CANL into a dominant state. Thus the bus is stuck in dominant state. No further communication is possible.

#### **Detection and Recovery**

The TXD permanent dominant time out will be activated and release the CANL and CANH drivers. However, at the next incoming dominant bit, the bus will then be stuck in dominant again. The recovery condition is same as the TXD dominant failure.

# <span id="page-20-0"></span>**EXTENDED DEVICE OPERATION**

The device has extended functionality which allows device control and diagnostic readings via the P\_SPI (Pseudo Serial Peripheral Interface), and using the STBY, EN and ERR pins.

#### **P\_SPI Operation**

The P\_SPI operation is similar to a standard SPI interface operation in slave mode. It uses the EN, STBY and ERR pins, which have the functions of MOSI, SCLK and MISO. There is no chip select (CS).

In write mode, the following functions and control are accessible:

- CAN driver slew rate selection
- ERR pin operation mode
- CAN wake-up mode
- CRANK mode operation

In read mode, the following flags are available:

- CAN bus detail diagnostic
- Local failure diagnostic
- Voltage monitoring
- Wake-up flags, wake pin level
- P\_SPI errors
- Device identification

#### **P\_SPI Diagram**

[Figure 17](#page-20-1) illustrates the P\_SPI operation. A clock signal should be generated on the STBY pin, EN input operates as Data In (MOSI) and the ERR output pin operates as Data Out (MISO).

In order to start a P\_SPI operation, the level at STBY should be low (1), as shown in [Figure 17.](#page-20-1) Bit D7 starts at the rising edge of STBY. Bit D7 level should be opposite to the level before. D7 is then internally sampled at the STBY falling edge.

The sampling of opposite level at (1) and (3) is the confirmation of a P\_SPI message start.

Then the P\_SPI bit D6 starts, and the device will drive the ERR pin to a level opposite to the one when P SPI started (5): this is the confirmation that the device has correctly detected a P\_SPI message start (acknowledgement).



 **Figure 17. : P\_SPI Message Start**

#### <span id="page-20-1"></span>**Full P\_SPI Message:**

[Figure 4](#page-8-0) describes the complete P\_SPI message and timing.

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#### **Distinction Between P\_SPI and Traditional Operation.**

The distinction between static device control and control via P\_SPI is performed by the duration of the EN and STBY level. If the EN and STBY levels change before a time of " $t_{DFV-TR}$ " then the device detects a P\_SPI operation. If the EN and / or  $\overline{\text{STBY}}$  levels are stable for a time longer than 15  $\mu$ s, then the device state will be changed according to EN / STBY level and device state diagram.

This means that the device mode change is done after a delay of typ  $t_{\text{DEV-TR}}$  and consequently the P\_SPI frequency operation should be faster than  $(1 / (2 * t_{DEV-TR}).$ With  $t_{DFV-TR}$  = 8.0 µs, the SPI equivalent frequency should be greater than 62.5 kHz.

#### **End of P\_SPI Message:**

At the P\_SPI message, the state of EN and STBY pins should be in line with the device mode expectation: example:

If the device is in Normal mode and should stay in Normal mode after the P\_SPI command, the EN and STBY pins should be 1,1 at end of the P\_SPI command.

If the device is in Listen Only mode, EN and STBY pins should be 0,1, in order to set or maintain the device in Listen Only mode.

#### **Time between 2 P\_SPI Message:**

A min delay of 15 µs should be observed between two P\_SPI messages.

The delay is measured between the last transition of the EN/STBY of the 1st message, and the 1st EN/STBY transition of the next message.

#### **P\_SPI Availability:**

The P\_SPI is operating only in Normal and Listen Only mode. It is not operating in Standby and Sleep modes.

[Table 8](#page-21-0) is the mapping of the P\_SPI register.



<span id="page-21-0"></span>**Table 8. P\_SPI Bit Mapping**

Low power mode definition: Standby, Go To Sleep and Sleep modes.









FUNCTIONAL DEVICE OPERATION *OPERATIONAL MODES*

![](_page_25_Picture_145.jpeg)

# **TYPICAL APPLICATIONS**

![](_page_26_Figure_2.jpeg)

Supported CAN terminations

![](_page_26_Figure_4.jpeg)

MC33902: WAKE Pin Configurations

![](_page_26_Figure_6.jpeg)

<span id="page-26-0"></span> **Figure 18. Typical Application and Bus Termination Options and WAKE Pin Configuration**

# **COMPARISON WITH COMPETITION 14 PIN HIGH SPEED CAN TRANSCEIVER**

The table below is a comparison between the MC33902 and the competition 14 pin high speed CAN transceiver having no embedded power supply.

![](_page_27_Picture_203.jpeg)

# **PACKAGING**

# *PACKAGE DIMENSIONS*

For the most current package revision, visit **[www.freescale.com](http://www.freescale.com)** and perform a keyword search using the **98ASB42565B** listed below.

![](_page_28_Figure_4.jpeg)

![](_page_28_Picture_81.jpeg)

EF-PIN (PB-FREE) 98ASB42565B ISSUE H

# **REVISION HISTORY**

![](_page_29_Picture_36.jpeg)

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![](_page_30_Picture_16.jpeg)

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